

October 7, 2002

VIA TELEFAX: 703-308-772<sup>4</sup>

To: Edgardo ORTIZ  
GROUP 2815  
United States Patent and Trademark Office

Dear Mr. ORTIZ

Re: FURUSAWA - U.S. Patent Appln. 09/939,761  
Filed August 28, 2001

Pursuant to our recent telephone conversation, we  
transmit hereafter the relevant papers.

Your prompt attention to this matter is sincerely  
appreciated.

Respectfully submitted,

YOUNG & THOMPSON

By \_\_\_\_\_  
Liam McDowell  
Attorney for Applicant  
Registration No. 44,231

9 pages including cover

PATENTS

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Koji FURUSAWA

Serial No. 09/939,761

GROUP 2815

Filed August 28, 2001

Examiner Edgardo Ortiz

SEMICONDUCTOR DEVICE

DRAFT AMENDMENT AFTER FINAL REJECTION

Commissioner for Patents

Washington, D.C. 20231

Sir:

Responsive to the Official Action of July 15, 2002,  
please amend the above-identified application as follows:

IN THE CLAIMS:

Amend the following claims:

--7. (amended) A semiconductor device comprising:

a substrate;

a first semiconductor chip on said substrate;

a second semiconductor chip overlying said first  
semiconductor chip;

a wiring layer between said first and second  
semiconductor chips, said wiring layer including a polyimide tape  
having a copper foil layer therein;

a plurality of bonding pads on said wiring layer, said  
substrate and said first and second semiconductor chips; and

a plurality of bonding wires for connecting said plural  
bonding pads to each other;

wherein said second semiconductor chip is mounted on